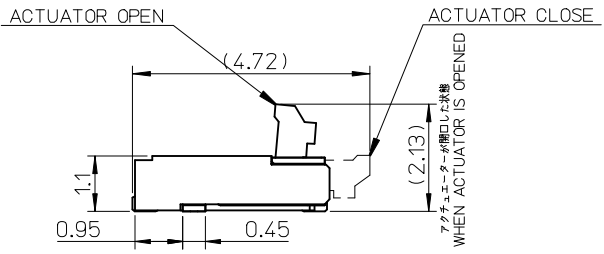
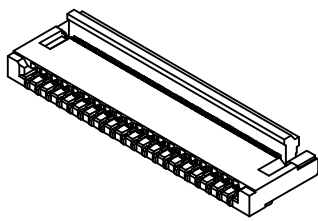


SECTION A-A SECTION B-B



部品構成  
PART COMPOSITION

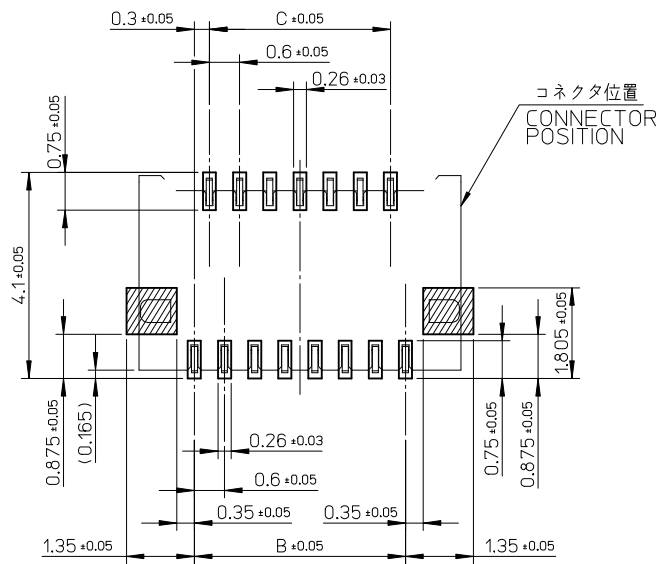
- ハウジング: 液晶ポリマー (LCP)、  
ガラス充填、UL94 V-0、ナチュラル(白)  
HOUSING: LIQUID CRYSTAL POLYMER (LCP),  
GLASS FILLED, UL94 V-0, NATURAL (WHITE)
- 奇数ターミナル: 銅合金  
ODD TERMINAL: COPPER ALLOY  
処理: ニッケル下地 部分金メッキ ニッケルストライプ(バリア)  
FINISH: PARTLY GOLD  
OVER NICKEL PLATING  
NI STRIPE (BARRIER)
- 偶数ターミナル: 銅合金  
EVEN TERMINAL: COPPER ALLOY  
処理: ニッケル下地 部分金メッキ ニッケルストライプ(バリア)  
FINISH: PARTLY GOLD  
OVER NICKEL PLATING  
NI STRIPE (BARRIER)
- アクチュエータ: 材質: ポリアミド(PA) 黒色 UL94V-0  
ACTUATOR  
MATERIAL: POLYAMIDE(PA)  
BLACK UL94-V0
- ネイル: 材質: 磷青銅  
NAIL MATERIAL: PHOSPHOR BRONZE  
処理: ニッケル下地 すすずめつき  
FINISH: TIN OVER NICKEL PLATING
- ELV及びRoHS適合品  
ELV & RoHS COMPLIANT



斜視図  
SCALE 5:1

6	4.8	5.4	7.6	502350-1900	19
4.8	3.6	4.2	6.4	502350-1500	15
D	C	B	A	EMBOSSED PACKAGE	極数
				オーダー番号 ORDER NO.	CIRCUITS
CONNECTOR SERIES No. 502350-**09					

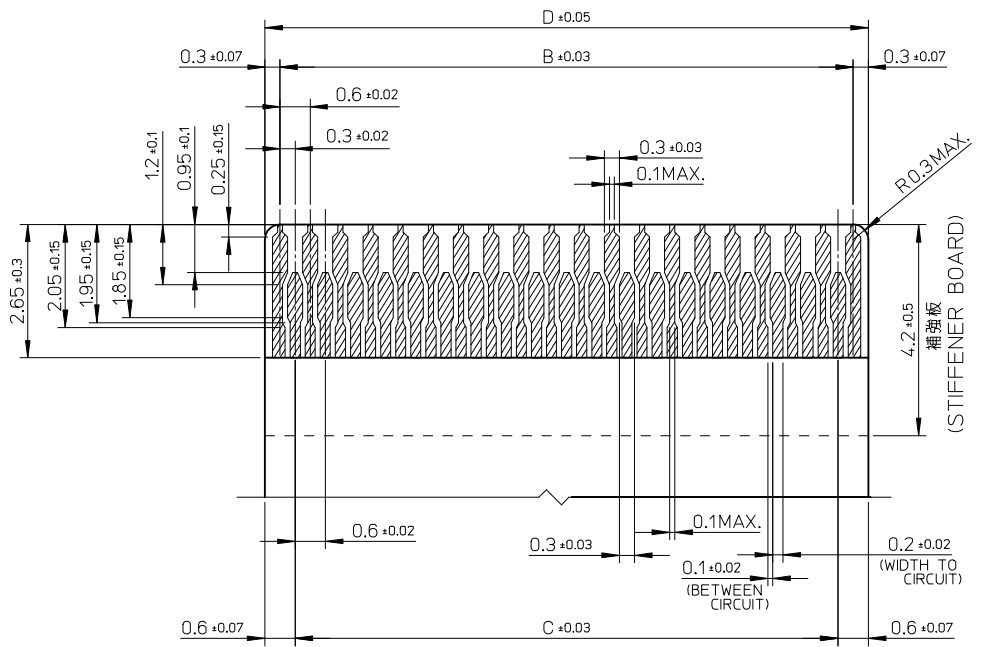
REVISED EC No: J2014-0958 DRWN: YOSHI I 01 2013/12/09 CHKD: YKOBAYASHI 02 2013/12/09 APPR: YNOGAWA 2013/12/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± 0.2	DRAWN BY T. HIRAYAMA	DATE 2009/01/05	TITLE 0.3 FPC CONN. E/O H=1.1 HOUSING ASSY WITH GUIDE		
	10 OVER 30 UNDER	± 0.25	CHECKED BY N. MATSUURA	DATE 2009/01/05	MATERIAL NO. SEE CHART		
	30 OVER	± 0.3	APPROVED BY KMORI KAWA	DATE 2010/10/25	DOCUMENT NO. SD-502350-001		
D	ANGULAR ±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	SHEET NO. 1 OF 2		
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							



参考基板レイアウト (マウント面)

P.C. BOARD PATTERN DIM.(REF.)

推奨メタルマスク厚さ : 0.1mm  
 RECOMMENDED METAL MASK THICKNESS : 0.1mm  
 推奨開口率 : 100%  
 APERTURE RATE : 100%

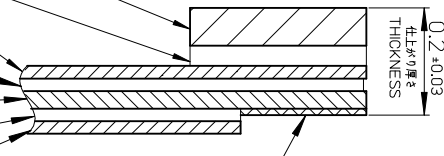


適合FPC推奨寸法

仕上がり厚さ : 0.2±0.03  
 APPLY FPC  
 RECOMMENDED DIM.  
 THICKNESS : 0.2±0.03

補強板 : ポリイミド  
 REINFORCE BOARD: POLYIMIDE  
 熱硬化接着剤  
 THERMOSETTING ADHESIVE  
 ベースフィルム : ポリイミド (25μm)  
 BASE FILM: POLYIMIDE (25μm)  
 熱硬化接着剤  
 THERMOSETTING ADHESIVE  
 導体部 : 銅箔 (35μm)  
 COPPER FOIL (35μm)  
 熱硬化接着剤  
 THERMOSETTING ADHESIVE  
 カバーレイ : ポリイミド (25μm)  
 COVER FILM: POLYIMIDE (25μm)

めっき : 金めっき (0.1μm以上)  
 下地ニッケル (1-5μm)  
 PLATING: GOLD (0.1μmMIN.)  
 NICKEL UNDER (1-5μm)



FPC構成推奨仕様  
 STRUCTURE OF FPC

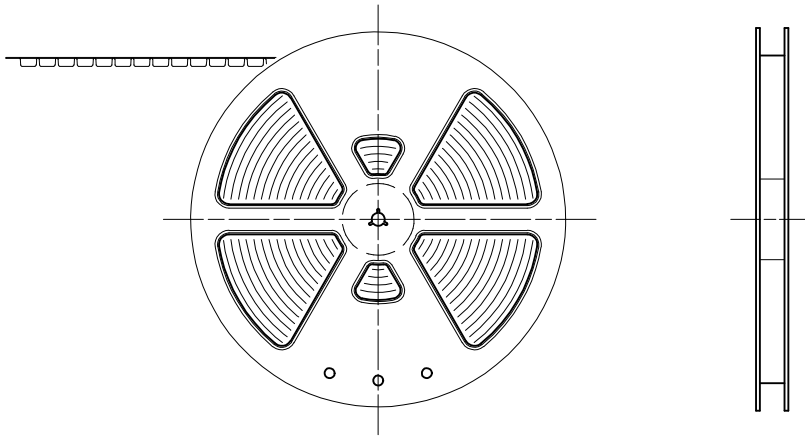
注記  
 NOTE

- 基板実装前にアクチュエータを操作しないで下さい。  
 PLEASE DO NOT OPERATE THE ACTUATOR BEFORE MOUNTING.
- 必ず基板に実装してからアクチュエータを操作して下さい。  
 PLEASE OPERATE THE ACTUATOR AFTER MOUNTING ON THE SUBSTRATE.
- FPCについて  
 ABOUT FPC  
 補強フィルム材質はポリイミドを推奨します。ベースフィルムは25μmを推奨します。  
 接着剤は熱硬化接着剤を推奨します。  
 尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。  
 RECOMMENDED STIFFENER MATERIAL: POLYIMIDE  
 RECOMMENDED BASE FILM THICKNESS: 25 MICROMETER  
 RECOMMENDED ADHESIVE: THERMOSETTING ADHESIVE  
 NOTE: PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

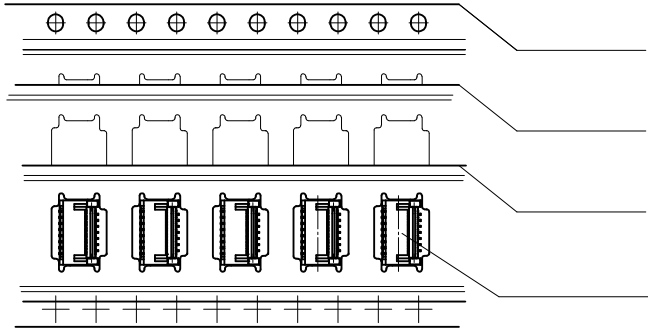
打抜き方向は導体側から補強板側を推奨致します。  
 導体部については軟銅箔35μmまたは50μmを推奨致します。  
 RECOMMENDED PUNCHER DIRECTION:  
 FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.  
 RECOMMENDED CONDUCTOR SPECIFICATION:  
 THICKNESS OF SOFT COPPER FOIL: 35MICROMETER OR 50 MICROMETER

- 平坦度は0.1以下  
 COPLANARITY TO BE 0.1 MAXIMUM

REVISED EC NO: J2014-0958 DRWN:AYOSHI 101 2013/12/09 CHKD:YKOBAYASHI 022013/12/09 APPR:YNOGAWA 2013/12/25	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION		
				MM ONLY		10:1	METRIC			
		10 UNDER	±0.2	DRAWN BY	DATE	TITLE				
		10 OVER 30 UNDER	±0.25	T. HIRAYAMA	2009/01/05	0.3 FPC CONN. E/O H=1.1 HOUSING ASSY WITH GUIDE				
	30 OVER	±0.3	CHECKED BY	DATE						
			N. MATSUURA	2009/01/05						
			APPROVED BY	DATE						
			KMORI KAWA	2010/10/25						
	ANGULAR	±3 °	MATERIAL NO.	DOCUMENT NO.						
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART 1		SD-502350-001				SHEET NO. 2 OF 2	
			SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						
			A3							



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**molex**